Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment





ATS Part#: ATS-51210D-C1-R0

Description: maxiFLOW™ maxiGRIP™ HS Assembly- LP, T766, BLACK- ANODIZED

Heat Sink Type: maxiFLOW
Heat Sink Attachment: maxiGRIP

Equivalent Part Number: ATS-51210D-C2-R0 Discontinued

*Image above is for illustration purpose only.

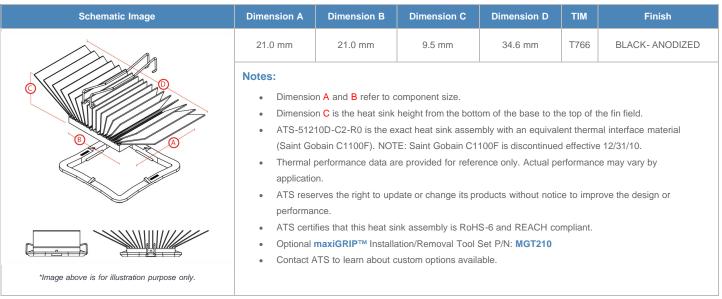
Features & Benefits

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- · Comes pre-assembled with high performance, phase changing, thermal interface material
- Designed for low profile components from 1.5 to 2.99mm
- "Keep-Out" Requirements: An "Un-Populated" border zone of 5mm around the component is necessary to facilitate the Installation/Removal of the maxiGRIP™. Please refer to the maxiGRIP™ Keep-Out Guidelines and maxiGRIP™ Installation/Removal Instructions for further details.

Thermal Performance

| AIR VELOCITY | | @200 LFM 1.0 M/S | @300 LFM 1.5 M/S | @400 LFM 2.0 M/S | @500 LFM 2.5 M/S | @600 LFM 3.0 M/S | @700 LFM 3.5 M/S | @800 LFM 4.0 M/S |
|--------------------|---------------|---------------------|---------------------|---------------------|---------------------|---------------------|---------------------|---------------------|
| THERMAL RESISTANCE | Unducted Flow | 12.01 °C/W | 9.66 °C/W | 8.35 °C/W | 7.47 °C/W | 6.83 °C/W | 6.33 °C/W | 5.93 °C/W |
| | Ducted Flow | 7.98 | n/a | n/a | n/a | n/a | n/a | n/a |

Product Detail



For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.

